

PART INFORMATION

Mfg Item Number	MC33887PFK
Mfg Item Name	PWR QFN 36 9*9*2.1P0.8

SUPPLIER

Company Name	Freescale Semiconductor Inc
Company Unique ID	14-141-7928
Response Date	2017-08-16
Response Document ID	6174A1.14
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DECLARATION

EU RoHS	Yes
Pb Free	No
HalogenFree	Yes
Plating Indicator	e4
EU RoHS Exemption(s)	7a

MANUFACTURING

Mfg Item Number	MC33887PFK
Mfg Item Name	PWR QFN 36 9*9*2.1P0.8
Version	ALL
Weight	0.513900
UoM	g
Unit Volume	EACH
J-STD-020 MSL Rating	3
Peak Processing Temperature	260 C
Max Time at Peak Temperature	40 seconds
Number of Processing Cycles	3

RoHS	
RoHS Directive	2011/65/EU
RoHS Definition	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) of homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material of Cadmium
RoHS Legal Definition	Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part(s) identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a RoHS restricted substance) in excess of the applicable quantity limit identified below. If a homogeneous material within the part(s) contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Suppliers liability and the Companys remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Suppliers Standard Terms and Conditions of Sale applicable to such part(s) shall apply.
RoHS Declaration	4 - Item(s) does not contain RoHS restricted substances per the definition above except for selected exemptions
Supplier Acceptance	Accepted
Signature	Daniel Binyon
Exemption List Version	2012/51/EU
Exemptions in this part	7a:Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)
List of Freescale Accepted Exemptions	<p>6(a) : Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35% lead by weight</p> <p>6(b) : Lead as an alloying element in aluminium containing up to 0.4% lead by weight</p> <p>6(c) : Copper alloy containing up to 4% lead by weight</p> <p>7(a) : Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead)</p> <p>7(b) : Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission, and network management for telecommunications</p> <p>7(c)-I : Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound</p> <p>7(c)-II : Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher</p> <p>7(c)-III : Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC</p> <p>7(c)-IV : Lead in PZT based dielectric ceramic materials for capacitors being part of integrated circuits or discrete semiconductors</p> <p>15 : Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages</p>

MATERIAL COMPOSITION

Homogeneous Material	Weight	SubstanceClass	Substance	CAS	Exemption	SubstanceWeight	UoM	SubPart PPM	SubPart%	ARTICLEPPM	ARTICLE%
Solder Die Attach	0.0053				7a		g				
Solder Die Attach		Antimony/Antimony Compounds	Antimony (metallic)	7440-36-0		0.0000001	g	18	0.0018	0	0
Solder Die Attach		Arsenic/Arsenic Compounds	Arsenic	7440-38-2		0.00000003	g	6	0.0006	0	0
Solder Die Attach		Lead/Lead Compounds	Lead	7439-92-1		0.00466416	g	880030	88.003	9076	0.9076
Solder Die Attach		Metals	Silver, metal	7440-22-4		0.00010595	g	19991	1.9991	206	0.0206
Solder Die Attach		Metals	Tin, metal	7440-31-5		0.00052976	g	99955	9.9955	1030	0.103
Die Encapsulant	0.2685						g				
Die Encapsulant		Bismuth/Bismuth Compounds	Bismuth	7440-69-9		0.00267829	g	9975	0.9975	5211	0.5211
Die Encapsulant		Plastics/polymers	Proprietary Material-Other Epoxy resins	-		0.02008729	g	74813	7.4813	39087	3.9087
Die Encapsulant		Solvents, additives, and other materials	Carbon Black	1333-86-4		0.00080362	g	2993	0.2993	1563	0.1563
Die Encapsulant		Solvents, additives, and other materials	Other organic phosphorous compounds	-		0.00254431	g	9476	0.9476	4950	0.495
Die Encapsulant		Plastics/polymers	Proprietary Material-Other phenolic resins	-		0.01473072	g	54863	5.4863	28664	2.8664
Die Encapsulant		Glass	Silica, vitreous	60676-86-0		0.22765577	g	847880	84.788	443012	44.3012
Copper Lead Frame	0.1682						g				
Copper Lead Frame		Metals	Copper, metal	7440-50-8		0.1640268	g	975189	97.5189	319180	31.918
Copper Lead Frame		Metals	Gold, metal	7440-57-5		0.00005954	g	354	0.0354	115	0.0115
Copper Lead Frame		Nickel (external applications only)	Nickel	7440-02-0		0.00375708	g	22337	2.2337	7310	0.731
Copper Lead Frame		Metals	Palladium, metal	7440-05-3		0.00035658	g	2120	0.212	693	0.0693
Lead Frame Assembly	0.0577						g				
Lead Frame Assembly		Metals	Aluminum, metal	7429-90-5		0.00000144	g	25	0.0025	2	0.0002
Lead Frame Assembly		Metals	Copper, metal	7440-50-8		0.0571787	g	990965	99.0965	111264	11.1264
Lead Frame Assembly		Metals	Gold, metal	7440-57-5		0.00001973	g	342	0.0342	38	0.0038
Lead Frame Assembly		Metals	Iron, metal	7439-89-6		0.00000144	g	25	0.0025	2	0.0002
Lead Frame Assembly		Metals	Manganese, metal	7439-96-5		0.00000144	g	25	0.0025	2	0.0002
Lead Frame Assembly		Nickel (external applications only)	Nickel	7440-02-0		0.00043696	g	7573	0.7573	850	0.085
Lead Frame Assembly		Metals	Palladium, metal	7440-05-3		0.00001719	g	298	0.0298	33	0.0033
Lead Frame Assembly		Metals	Zirconium, metal	7440-67-7		0.0000431	g	747	0.0747	83	0.0083
Silicon Semiconductor Die	0.0094						g				
Silicon Semiconductor Die		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%)	-		0.000188	g	20000	2	365	0.0365
Silicon Semiconductor Die		Glass	Silicon, doped	-		0.009212	g	980000	98	17925	1.7925
Bonding Wire, Other	0.0048						g				
Bonding Wire, Other		Metals	Copper, metal	7440-50-8		0.0047376	g	987000	98.7	9218	0.9218
Bonding Wire, Other		Metals	Palladium, metal	7440-05-3		0.0000624	g	13000	1.3	121	0.0121

LINKS

MCD LINK	
NXP website	http://www.nxp.com
GENERAL ENVIRONMENTAL COMPLIANCE LINKS	
RoHS signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-ROHS-DECLARATION.pdf
China RoHS	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/china-rohs:ENV_CHINA_ROHS_STRATEGY
REACH signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-REACH-STATEMENT.pdf
ELV signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-ELV-STATEMENT.pdf
Conflict Minerals statement	http://www.nxp.com/files/corporate/doc/support_info/NXP-STATEMENT-CONFLICT-MINERALS.pdf
NXP ENVIRONMENTAL INFORMATION	
Environmental Compliance website	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization:ABUENVPRFPRDX
FAQ	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/eco-product-faqs:ENVIRON_FAQ
Technical Service Request	http://www.nxp.com/support/sales-and-support:SUPPORTHOME
LINKS TO BLANK IPC1752 FORMS	
Blank IPC1752 v1.1 Form	http://www.NXP.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v1.1_MCD_Template.pdf

IPC1752 XML LINKS

http://www.freescale.com/mcdfs/MC33887PFK_IPC1752_v11.xml

http://www.freescale.com/mcdfs/MC33887PFK_IPC1752A.xml